

Title (en)

Method for forming thick film layer of micro injecting device

Title (de)

Verfahren zum Bilden einer Dickfilmschicht für Mikrospritzvorrichtung

Title (fr)

Procédé de formation d'une couche à film épais pour micro-dispositif d'injection

Publication

EP 0999057 A2 20000510 (EN)

Application

EP 99308721 A 19991103

Priority

RU 98119888 A 19981103

Abstract (en)

A method for forming a thick film layer (30) of micro injecting device is disclosed in which a thin film layer (31') is formed on a substrate (1), a thick film layer (32') is formed on the thin film layer (31') without performing additional heat-treatment, and the thin film layer (31') and thick film layer (32') formed sequentially on the substrate are simultaneously heat-treated, to thereby complete a single thick film layer (30). The single thick film layer (30) is formed by a sequential coating process without being interfered by heat-treatment, thereby eliminating an isolating line. As a result, an overall durability of thick film layer (30) can be significantly enhanced. <IMAGE>

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IPC 8 full level

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CPC (source: EP KR)

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Citation (applicant)

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